SMD SILICON PHOTO DIODES

BL-LS3528A0S1PD

Features:

- 3.5mmx2.8mm SMD, 1.9mm THICKNESS PLCC2 package, SILICON PHOTO DIODES
- Choice of various viewing angles.
- Diffused and Water clear lens are available.
- Fast response time.
- High photo sensitivity.
- Small junction capacitance.
- The epoxy package itself is an IR filter, spectrally matched to GaAs or GaAlAs IR emitter.
- PACKAGE: 2KPCS/REEL.
- RoHs Compliance

■ Applications:

·High speed photo detector
·Camera
·Infrared remote controller for TVs VCR, audio equipment, air conditioner, etc.

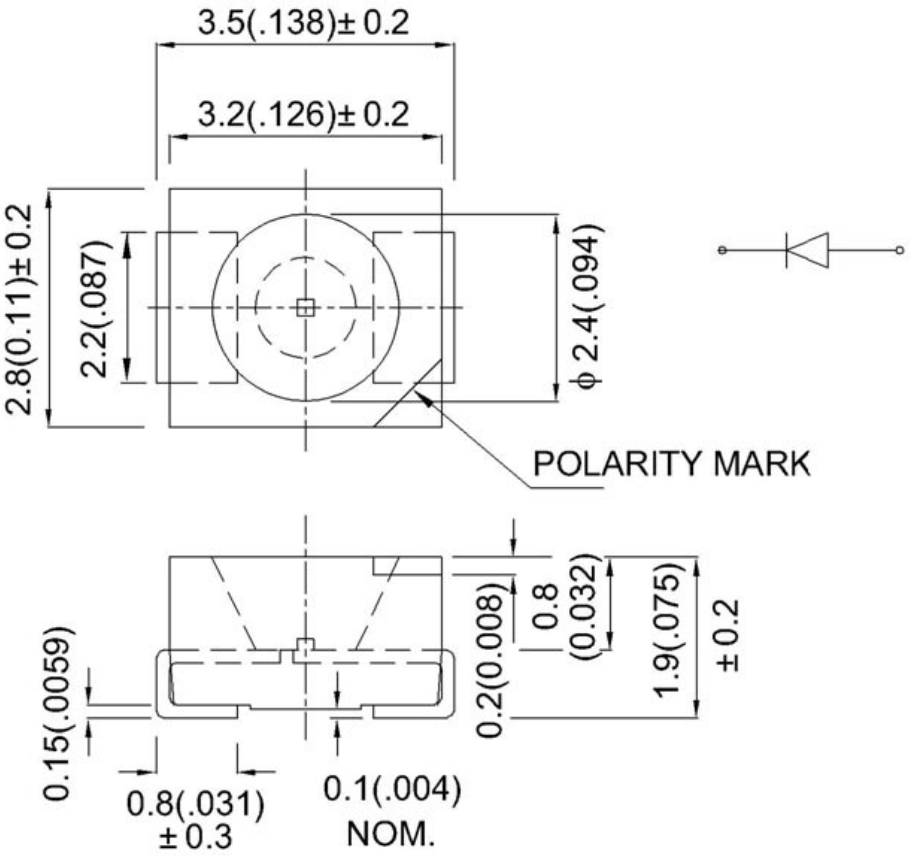
■ Absolute Maximum Ratings at Ta=25°C

Parameter	Symbol	Rating	Unit
Power Dissipation	P_d	160	mW
Reverse Voltage	V_R	35	V
Operation Temperature	T_{OPR}	-40 to +100	°C
Storage Temperature	T_{STG}	-40 to +100	°C
Lead Soldering Temperature	TSOL	Max.260± 5 °C for 3 sec Max. (1.6mm from the base of the epoxy bulb)	°C

■ Electronic Optical Characteristics at Ta=25°C

Items	Symbol	Min.	Typ.	Max.	Unit	Condition
Wavelength of Peak Sensitivity	?$_P$	-	900	-	nm	-
Open Circuit Voltage	V_{OC}	-	0.40	-	V	H=5mW/cm^2 ?$_P$=900nm
Short Circuit Current	I_{SC}	-	2	-	uA	
Reverse Light Current	I_L	-	3.5	-	uA	H=5mW/cm^2 ?$_P$=900nm V_R=5V
Reverse Dark Current	ID	-	-	10	nA	H=0mW/cm2 V_R=10V
Reverse Break down Voltage	V_{BR}	35	170	-	V	H=0mW/cm2 I_R=100uA
Viewing angle	2?1/2	-	120	-	Deg	
Rise/Fall Time	Tr/T_f	-	6/6	-	nS	R_L=1000O V_R=10V

■ **Package configuration & Internal circuit diagram**

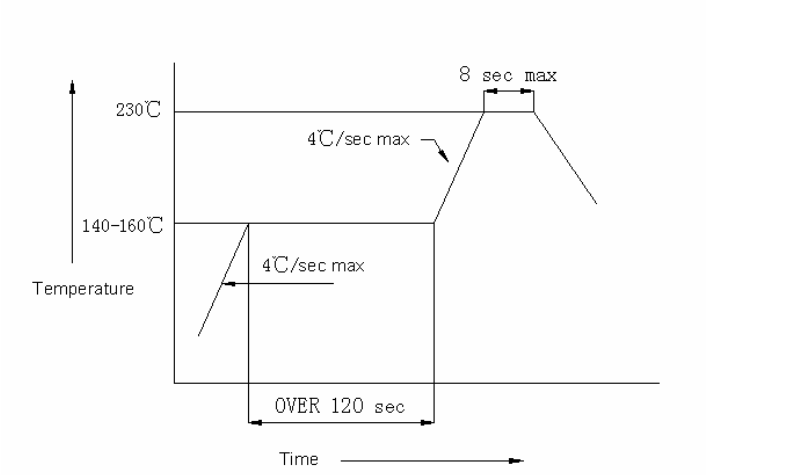


Notes:
1. All dimensions are in millimeters (inches)
2. Tolerance is ± 0.25(0.01")unless otherwise noted.
3. Specifications are subject to change without notice.

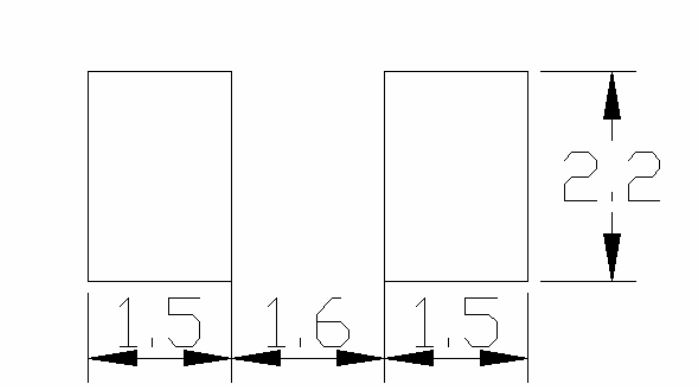
■ Tape Specifications

Smt Reflow Solding Instructions

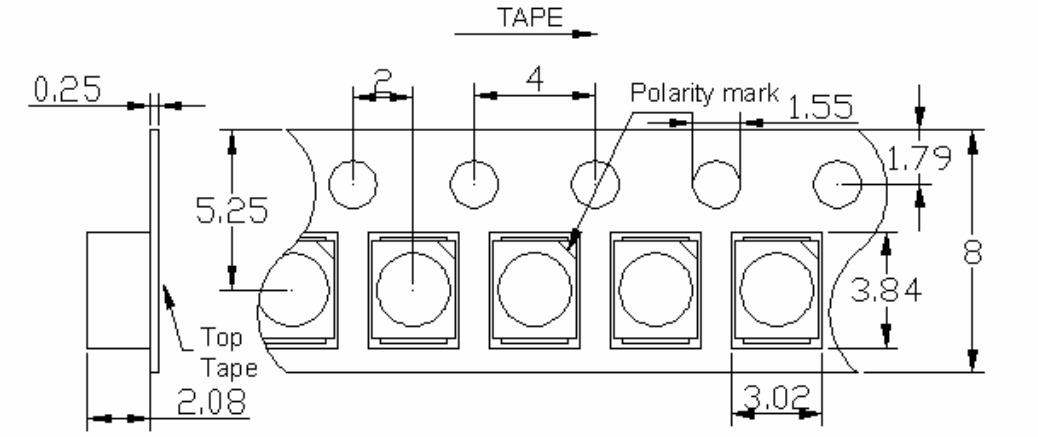
Number of reflow process shall be less than 2 times
and cooling process to normai temperature is required
between first and second soldering process



Recommended Soldering Pattern
(Units:mm)



Tape Specifications
(Units:mm)



■ Packing and weighting